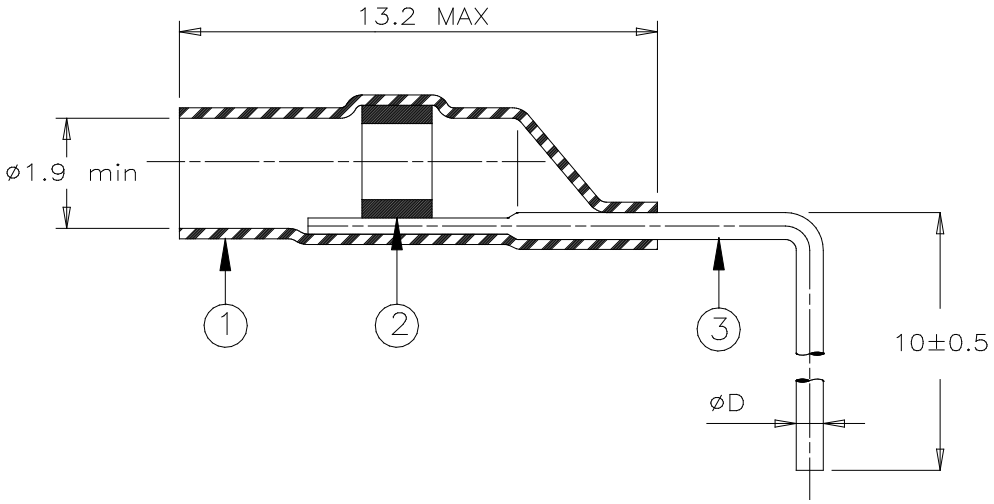
# CUSTOMER DRAWING




| Product Name | øD | øX |
|---|---|---|
| B-801-06 | 0.68 | 0.8 |
| B-801-08 | 0.88 | 1 |

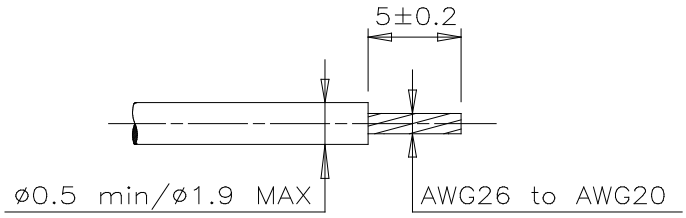
**MATERIALS**

1. INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked modified polyvinylidene fluoride.
2. SOLDER PREFORM WITH FLUX:
   SOLDER: TYPE Sn62 Pb36 Ag2 per ANSI-J-STD-006.
   FLUX: TYPE ROL0 per ANSI-J-STD-004.
3. PIN: Phosphor bronze coated with Sn60 Pb40 solder alloy.

**APPLICATION**

1. These controlled soldering devices are designed for termination of a tin or silver plated stranded AWG26, AWG24 and AWG22 conductor having an insulation rated for at least +125°C on a PC board with øX diameter hole. If AWG20 wire is used, pre-tinning is recommended.
2. Temperature range: -55°C to +150°C. For application tooling, contact your local TE Connectivity technical service.

For best results, prepare the wire as shown:




| | | | | | |
|---|---|---|---|---|---|
| TE connectivity | | ***Raychem*** THERMOFIT DEVICES | TITLE: **PINPAK* DEVICE FOR PCB TERMINATION** | | |
| Unless otherwise specified dimensions are in millimeters. [Inches dimensions are shown in brackets] | | | DOCUMENT NO.: **B-801-0X** | | |
| TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A | ANGLES: N/A ROUGHNESS IN MICRON | TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application. | REV: 3 | DATE: 09-Mar-2020 | |
| DRAWN BY: M. FORONDA | DATE: 22-Mar-1999 | ECO: ECO-20-003687 | SCALE: NTS | SIZE: A | SHEET: 1 of 1 |

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